

IN THE CLAIMS

Please amend claim 44 to read as follows:

44. (Amended) A method for manufacturing semiconductor devices, the method comprising:

preparing a semiconductor wafer with a first surface and a second surface, the second surface being opposite to the first surface, wherein the first surface has a plurality of circuit elements formed thereon;

forming a plurality of electrodes on the first surface, the electrodes being connected to the circuit elements;

inserting the semiconductor wafer into a burn-in apparatus;

testing the circuit elements in the burn-in apparatus for electrical function, through the electrodes, with the second surface of the semiconductor wafer exposed to convective air in the burn-in apparatus; and

dividing the semiconductor wafer into the plurality of semiconductor devices.